

SMD Comm COG HV, Ceramic, 330 pF, 5%, 630 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1206



**Dimensions**

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1mm +/-0.10mm
B	0.5mm +/-0.25mm

**Packaging Specifications**

Packaging:	T&R, 330mm, Plastic Tape
Packaging Quantity:	10000

**General Information**

Series:	SMD Comm COG HV
Style:	SMD Chip
Description:	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features:	Ultra-Stable, Low Loss, Class I
RoHS:	Yes
Termination:	Tin
Marking:	No
AEC-Q200:	No
Shelf Life:	78 Weeks
MSL:	1

**Specifications**

Capacitance:	330 pF
Measurement Condition:	1 MHz 1.0Vrms
Capacitance Tolerance:	5%
Voltage DC:	630 VDC
Dielectric Withstanding Voltage:	945 VDC
Temperature Range:	-55/+125°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor:	0.1% 1 MHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	100 GOhms